Liquid flux FLAST

Flux is a fusing agent required to remove oxides from the surface of the metal before soldering.

LEAD-FREE SOLDER EVASOL® 鉛フリーはんだエバソル

WATER-SOLUBLE FLUX

Parts No.	Flux pH	Viscosity (Pa・s)	Specific gravity	Halogen content(%)	Cleaning after soldering	Solvent	Rinsing solution	Features
A	1.0	2.3×10^{-3}	1.384	33.4	Necessary	Pure water	Hot pure water	Applicable to materials difficult to solder. With broad soldering temperature range of 130 to 450℃. The spreading rate is 95% for copper, 95% for brass, 90% for nickel 88% for stainless steel, and 90% for steel.
S	2.0	41.4×10^{-3}	1.500	0.00	Necessary	Pure water	Hot pure water	Especially for stainless steel, but applicable to copper, nickel and steel as well. Capable of soldering at relatively low temperature (about 250℃). Dissolves above 350℃, making soldering impossible. Umit soldering temperature to below 300℃. The spreading rate is 92% for copper, 92% for brass,90% for nickel, 90% for stainless steel, and 91% for steel.
D	2.3	1.2×10^{-3}	1.040	0.36	Unnecessary	Pure water	—	For terminating copper wires; non-corrosive. To terminate wires, apply flux, then dip the wires in a 350～450℃ solder bath. The spreading rate is 92% for copper.
DA	3.2	2.6×10^{-3}	0.978	0.18	Unnecessary	Pure water	—	Even more reliable product than D. Non-corrosive and for terminaling wires. The spreading rate is 90% for copper.
H	2.0	3.2×10^{-3}	1.440	32.0	Necessary	Pure water	Hot pure water	Capable of high-strength soldering of stainless steel, zinc, zinc alloys, steel, nickel, brass, copper and other metals. Applicable to stained glass as well if diluted with water. The spreading rate is 96% for copper.
I	3.6	1.1×10^{-3}	1.000	0.9	Unnecessary	Pure water	—	For terminaling leads. Decomposed at soldering temperature but is non-corrosive. The spreading rate is 94% for copper.
G	2.0	440×10^{-3}	1.240	1.3	Necessary	—	Hot pure water	Have hight viscosity and can apply by brush. Applicable tonickel, copper, iron and other metals. The spreading rate is 90% for copper.
IH2	5.0	320×10^{-3}	1.240	0.78	Unnecessary	—	—	For electric light bulb bases (brass).

Remarks
Specific gravity and viscosity in the above table are those at 20℃.

LIQUID RESIN FLUX

Parts No.	Solid content(%)	Viscosity (Pa・s)	Specific gravity	Halide content(%)	Cleaning after soldering	Spreading ratio(%)	Solvent	Features
R	35	4.0×10^{-3}	0.870	0.25	Unnecessary	94	Solvent R	For general electronic purposes. Greatly Improves solder reliability. Suitable for soldering at high temperatures in particular.
R50	50	12.0×10^{-3}	0.927	0.35	Unnecessary	95	Solvent RD	Applicable to materials difficutt to solder such as nickel and brass.
RS35	35	4.5×10^{-3}	0.882	0.00	Unnecessary	95	Solvent R	Fluorine based flux provides very efficient soldering and is suitable for use on nickel plated parts and the like.
RM35	35	4.2×10^{-3}	0.870	0.00	Unnecessary	90	Solvent R	MIL-RMA type, for precision electronic parts.

Remarks
Specific gravity and viscosity in the above table are those at 20℃.

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